EWM104-BT3095 Product Specification

QCC3095 DAC/I2S/SPDIF Wireless Bluetooth Audio Module



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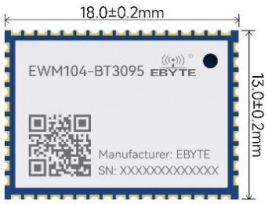
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Chapter 1 Overview

1.1 Introduction

The EWM104-BT3095 is a high-performance, low-power, and cost-effective Bluetooth BLE 5.4 audio module developed by EBYTE. It uses Qualcomm's QCC3095 chip as the main controller, providing a system with on-chip Bluetooth, audio, and a programmable application processor. It integrates high-performance analog and digital audio codecs, Class AB and Class D headphone drivers, advanced power management, flexible interface protocols, and programmable input/output (PIO).



EWM104-BT3095

1.2 Features and Functions

- Compliant with the Bluetooth 5.4 protocol specification;
- Supports apt-X, apt-X HD, AAC, and SBC audio codecs;
- Supports stereo audio;
- Supports simultaneous connection to two transmitters;
- 240 MHz Qualcomm Kalimba™ audio DSP;
- 80 MHz application development processor;
- Flexible QSPI flash programming platform;
- Fully programmable digital ANC;
- Firmware supports analog output, I2S output, and SPDIF output;
- Supports USB Audio function;
- USB-Audio supports up to 24-bit/96 kHz; Bluetooth audio supports up to 24-bit/48 kHz (aptX HD) and 24-bit/96 kHz (LDAC; aptX Adaptive requires a license);
- Supports mobile phone OTG function: when the module is configured as a USB Audio slave device, it can receive USB digital audio output from an Android phone acting as the OTG host;
- Supports serial port commands for volume control, previous/next track, and play/pause functions (effective in both Bluetooth and USB Audio modes);
- High-performance analog and digital audio codecs;
- Differential headphone output mode, supporting Class AB and Class D.

1.3 Applications

- High-quality stereo headphones;
- Portable Bluetooth stereo speakers;
- TWS Bluetooth headphones, Bluetooth speakers, etc.

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Chapter 2 Specifications

2.1 Performance Parameters

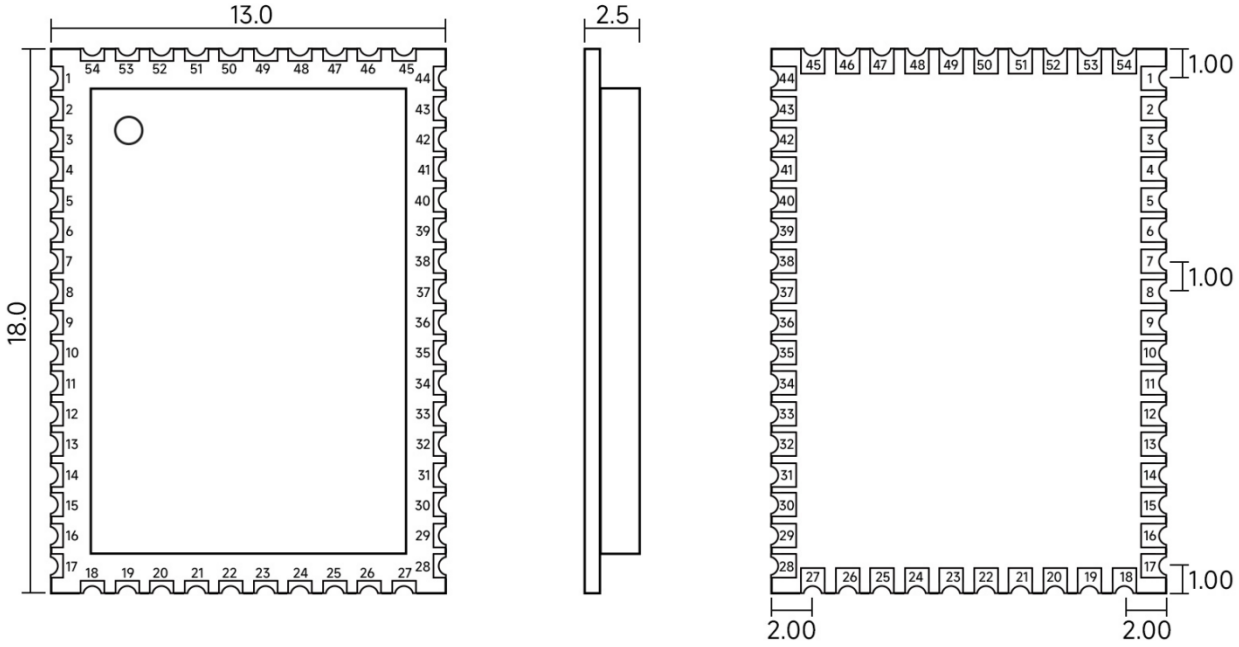
Main Parameters		Performance			Remarks
		Min.	Typ.	Max.	
Operating Voltage VCHG (V)		4.0	5	5.5	Exceeding 6.5 V will permanently damage the module
Operating Voltage VBAT (V)		3.0	3.7	4.3	Exceeding 4.3 V will permanently damage the module
Communication Level (V)		1.8	3.3	3.6	The logic level is determined by the VDD_PADS level
Operating Temperature (℃)		-40	20	+85	Industrial-grade design
Operating Frequency Band (MHz)		2402	-	2480	Supports the standard frequency band specified by the Bluetooth protocol
Power Consumption	Unconnected Current (mA)	-	6.5	-	Bluetooth is discoverable
	Connected and Audio Playback Current (mA)	-	6.0	-	Bluetooth is connected but no music is playing
	Shutdown Current (uA)	-	21	-	When powered by VBAT only
Maximum Transmit Power (dBm)		-	8	-	
Receiver Sensitivity (dBm)		-	-97.0	-	Basic Rate

Main Parameters	Description	Remarks
Reference Distance	200m	Clear and open environment, communicating with a mobile phone
Package Type	Surface-mount	
Output Interface	DAC/I2S/SPDIF	DAC/I2S/SPDIF output switching
Communication Interface	UART	
Interface Type	Castellated holes	1.00 mm pitch
Dimensions	13*18mm	±0.2mm
Antenna Interface	Castellated holes	Equivalent impedance approximately 50 Ω
Weight	1.0g	±0.1g
Operating Temperature:	-40~+85℃	Industrial-grade design

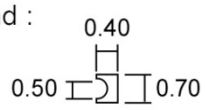
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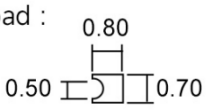
2.2 Mechanical Dimensions and Pin Definitions



Top pad :



Bottom pad :



Unit : mm
Pad quantity : 54
Tolerance value : X.X±0.2mm
X.XX±0.05mm

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Pin No.	Pin Name	Power	Pin Direction	Pin Description
1	GND	-	GND	Ground
2	PIO21	VDD_PADS	I/O	Programmable I/O 21. When IO21 is pulled high, SPDIF output is selected. Other function: PCM_DOUT2
3	PIO20		I/O	Power amplifier enable pin, programmable I/O 20
4	PIO19		I/O	Programmable I/O 19 Other function: PCM_DIN0
5	PCM_DOUT0		I/O	Programmable I/O 18, connected to I2S_DIN or SPDIF_OUT
6	PCM_SYNC		I/O	Programmable I/O 17, connected to I2S_LRCK
7	PCM_CLK		I/O	Programmable I/O 16, connected to I2S_BCK
8	PCM_MCLK		I/O	Programmable I/O 15, connected to I2S_MCK
9	USB_DN	-	I/O	USB data negative
10	USB_DP	-	I/O	USB data positive
11	SYS_CTRL	VBAT	I	After being held high for 6 seconds, then switched to low, powers the module on/off and automatically enters pairing mode
12	VBAT	VBAT	I	Battery interface, battery voltage input, 3.0~4.3 V
13	CHG_EXT	VCHG	I	External charging control, external charging transistor current control
14	VCHG	VCHG	I	Charging interface, battery charging input, 4.0~5.5 V
15	LED3	-	I/O	Analog/digital input, open-drain LED output
16	LED2	-	I/O	Analog/digital input, open-drain LED output, flashes during pairing
17	GND	-	GND	Ground
18	LED1	-	I/O	Analog/digital input, open-drain LED output
19	LED0	-	I/O	Analog/digital input, open-drain LED output
20	PIO7	VDD_PADS	I/O	Programmable I/O 7, UART_RX
21	PIO4		I/O	Button PIO[4], short press for Play/Pause
22	PIO3		I/O	Button PIO[3], short press to increase volume, long press to continuously increase volume, double press for next track
23	PIO6		I/O	Programmable I/O 6, UART_TX
24	PIO5		I/O	Button PIO[5], short press to reconnect, long press for 3 seconds to disconnect, 6 seconds to enter pairing mode, 8 seconds to clear the list
25	PIO8		I/O	Programmable I/O 8. When IO8 is pulled high, DAC output is selected
26	PIO2		I/O	Button PIO[2], short press to decrease volume, long press to continuously decrease volume, double press for previous track
27	RESET#/PIO1		I/O	Button PIO[1], module reset control button; press to reset
28	GND	-	GND	Ground
29	VDD_PADS	-	PWR	PIO power input, 1.8 V/3.3 V PIO power supply
30	1V8_SMPS	-	PWR_OUT	Power output, 1.8 V power output
31	SPKR_N	-	O	Speaker differential output, right channel negative
32	SPKR_P	-	O	Speaker differential output, right channel positive
33	SPKL_N	-	O	Speaker differential output, left channel negative
34	SPKL_P	-	O	Speaker differential output, left channel positive
35	MIC_BIAS	-	O	Analog output, microphone bias output
36	MIC1_N	-	I	Analog input, microphone differential input 1 negative
37	MIC1_P	-	I	Analog input, microphone differential input 1 positive
38	MIC2_N	-	I	Analog input, microphone differential input 2 negative
39	MIC2_P	-	I	Analog input, microphone differential input 2 positive
40	MIC3_N	-	I	Analog input, microphone differential input 3 negative
41	MIC3_P	-	I	Analog input, microphone differential input 3 positive
42	MIC4_N	-	I	Analog input, microphone differential input 4 negative
43	MIC4_P	-	I	Analog input, microphone differential input 4 positive
44	GND	-	GND	Ground
45	GND	-	GND	Ground
46	RF_PORT	-	O	External antenna
47	GND	-	GND	Ground
48	PIO39	VDD_PADS	I/O	Programmable I/O 39 Other function: QSPI2_IO3
49	PIO38		I/O	Programmable I/O 38 Other function: QSPI2_CS#
50	PIO37		I/O	Programmable I/O 37 Other function: QSPI2_IO1
51	PIO36		I/O	Programmable I/O 36. When IO36 is pulled high, USB input is selected; when

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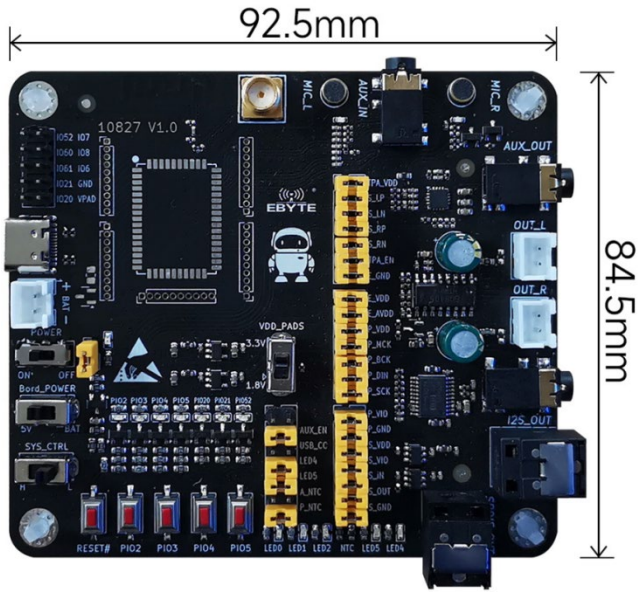
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Pin No.	Pin Name	Power	Pin Direction	Pin Description
				pulled low, AUX input is selected. Other function: QSPI2_IO2
52	PIO35		I/O	Programmable I/O 35 Other function: QSPI2_CLK
53	PIO34		I/O	Programmable I/O 34 Other function: QSPI2_IO0
54	PIO22		I/O	Programmable I/O 22 Other function: PCM_DIN1

Chapter 3 Quick Start

This quick-start procedure requires the use of our test baseboard.

3.1Power-On and Pairing



The EWM104-BT3095 test baseboard does not include the module by default. Customers can purchase the module and adapter board separately according to their requirements.

After soldering the module onto the adapter board, insert the adapter board into the test baseboard through the pin headers. Use the Type-C interface for power supply. After the power indicator lights up, set the SYS_CTRL DIP switch to the right. When the DIP switch is turned on for 2 seconds, there will be one beep; after 6 seconds, there will be three beeps. At this point, switch it back to the original position. The module will power on and automatically enter Bluetooth pairing mode.

Then, connect your phone to the module via Bluetooth and play music. The music can then be heard through the connected audio output device.

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3.2 Audio Input and Output

3.2.1 Audio Input:

1. When IO36 is pulled low: AUX input. At this time, only AUX input can be used.

Connect the computer's AUX interface as the audio input. (The IO36 pin must be pulled low; it is low by default and can be left floating.)

Use the speaker as an I2S output device. (When using I2S as the output, the IO8 and IO21 pins must be pulled low; they are low by default and can be left floating.) Play audio on the computer, and the speaker will output the audio. The buttons can be used to pause/play, switch to the next/previous track, and increase/decrease the volume.

2. When IO36 is pulled high and USB is connected: USB input. (Input priority: USB > Bluetooth)

Connect the computer's USB interface as the audio input. (The computer must have the corresponding driver installed, and the IO36 pin must be pulled high.)

Use the speaker as an I2S output device. (When using I2S as the output, the IO8 and IO21 pins must be pulled low; they are low by default and can be left floating.) Play audio on the computer, and the speaker will output the audio. The buttons can be used to pause/play, switch to the next/previous track, and increase/decrease the volume.

3. When IO36 is pulled high and USB is not connected: Bluetooth input

Connect the phone via Bluetooth as the audio input. (The IO36 pin must be pulled high.)

Use the speaker as an I2S output device. (When using I2S as the output, the IO8 and IO21 pins must be pulled low; they are low by default and can be left floating.) Play audio on the computer, and the speaker will output the audio. The buttons can be used to pause/play, switch to the next/previous track, and increase/decrease the volume.

3.2.2 Audio Output:

1. IO8 pulled high, IO21 pulled high/low: DAC output

Use the speaker as a DAC output device. (When using DAC as the output, the IO8 pin must be pulled high.) Use the phone to play audio, and the speaker will output the audio. The buttons can be used to pause/play, switch to the next/previous track, and increase/decrease the volume.

2. IO8 pulled low, IO21 pulled low: I2S output

Use the speaker as an I2S_OUT output device. (When using I2S as the output, the IO8 and IO21 pins must be pulled low; they are low by default and can be left floating.) Use the phone to play audio, and the speaker will output the audio. The buttons can be used to pause/play, switch to the next/previous track, and increase/decrease the volume.

3. IO8 pulled low, IO21 pulled high: SPDIF output

Use the speaker as an SPDIF output device. (When using SPDIF as the output, the IO21 pin must be pulled high.) Use the phone to play audio. The speaker can normally play the audio output from the phone. The buttons can be used to pause/play, switch to the next/previous track, and increase/decrease the volume.

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3.2Multi-Connection Function

The module supports simultaneous connection to two Bluetooth transmitting devices.

After the first Bluetooth device is connected, move the SYS_CTRL switch to the right for 6 seconds and then switch it back. Enter pairing mode again to connect the second Bluetooth device.

3.4 Button Control

PIO2: Short press to decrease the volume; press and hold to continuously decrease the volume; double press to play the previous track

PIO3: Short press to increase the volume; press and hold to continuously increase the volume; double press to play the next track

PIO4: Short press to play/pause

PIO5: Short press to reconnect; press and hold for 3 seconds to disconnect; press and hold for 6 seconds to enter pairing mode; press and hold for 8 seconds to clear the pairing list

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Chapter 4 AT Commands

4.1 Description

1、IO6 is UART_TX, and IO7 is UART_RX.

2、The default baud rate supported by the module's UART interface is 115200 bps, with 8N1 format.

4.2 Command Description

4.2.1 AT Test Command

Command	Response	Example
AT	OK	Send: AT Return: OK
Description: AT link test		

4.2.2 Volume Setting

Command	Response	Example
AT+VOL=?	VOL=<value>	Send: AT+VOL=? Return: VOL=70
AT+VOL=<value>	OK	Send: AT+VOL=66 Return: OK
AT+VOL=UP	OK	Send: AT+VOL=UP Return: OK
AT+VOL=DOWN	OK	Send: AT+VOL=DOWN Return: OK
Description: =<value> can be set within the range of 0–127. =UP increases the volume by 8 each time. =DOWN decreases the volume by 8 each time. The volume can only be adjusted when audio is being output.		

4.2.3 Play Next Track

Command	Response	Example
AT+FORWARD	OK	Send: AT+FORWARD Return: OK
Description: None		

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4.2.4 Play Previous Track

Command	Response	Example
AT+BACKWARD	OK	Send: AT+BACKWARD Return: OK
Description: None		

4.2.5 Play/Pause

Command	Response	Example
AT+PLAYPAUSE	OK	Send: AT+PLAYPAUSE Return: OK
Description: The playback status toggles each time this command is used.		

4.2.6 Restore Factory Parameters

Command	Response	Example
AT+RESTORE	OK	Send: AT+RESTORE Return: OK
Description: None		

4.2.7 Read Version Number

Command	Response	Example
AT+VER	OK	Send: AT+VER Return: 7588-0-10
Description: None		

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Chapter 5 Hardware Circuit Design and Requirements

5.1 Hardware Design Requirements

- **SYS_CTRL must not be directly pulled up to VBAT through a resistor.** SYS_CTRL controls the power-on/off of the Bluetooth chip. The power-on operation can only be performed after the chip has completed its power-on initialization, and a simple RC delay circuit must not be used, as it is unstable. For the relevant delay circuit, please refer to the recommended circuit in the official user manual.
- The module's audio output and MIC input are both differential circuits. For the relevant hardware design, please refer to our company's hardware design circuit.
- High-frequency digital traces, high-frequency analog traces, and power traces must avoid routing underneath the module. If routing underneath the module is unavoidable, assuming that the module is soldered on the Top Layer, ground copper should be poured over the contact area of the module on the Top Layer (with the entire area covered by copper and properly grounded). The traces should be routed on the Bottom Layer, as close as possible to the digital section of the module.
- Assuming that the module is soldered or placed on the Top Layer, freely routing traces on the Bottom Layer or other layers is also incorrect, as this will affect the module's spurious emissions and receiving sensitivity to varying degrees.
- It is recommended to power the module via USB or a battery. The power supply ripple should be kept as low as possible, and the module must be reliably grounded.
- Please pay attention to the correct connection of the positive and negative power terminals. Reverse connection may result in permanent damage to the module.
- Please check the power supply and ensure that it is within the recommended operating voltage range. Exceeding the maximum voltage may cause permanent damage to the module.
- When designing the power supply circuit for the module, it is generally recommended to reserve more than 30% margin, which is beneficial for the long-term stable operation of the complete device.
- The module should be kept as far away as possible from components with strong electromagnetic interference, such as power supplies, transformers, and high-frequency traces.
- If there are components generating significant electromagnetic interference around the module, they may also greatly affect the module's performance. It is recommended to keep such components at an appropriate distance from the module according to the interference strength. If conditions permit, appropriate isolation and shielding can be implemented.
- If there are traces generating significant electromagnetic interference around the module (such as high-frequency digital traces, high-frequency analog traces, and power traces), they may also greatly affect the module's performance. It is recommended to keep such traces at an appropriate distance from the module according to the interference strength. If conditions permit, appropriate isolation and shielding can be implemented.
- The module antenna must not be installed inside a metal enclosure, as this will severely reduce the transmission distance.

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Chapter 6 Frequently Asked Questions

6.1 Unsatisfactory Transmission Distance

- When there are obstacles along the line-of-sight communication path, the communication distance will be reduced accordingly.
- Temperature, humidity, and co-channel interference may increase the packet loss rate.
- The ground can absorb and reflect radio waves, resulting in poorer test performance when testing close to the ground.
- Seawater has a very strong ability to absorb radio waves, so test performance near the seaside is poor.
- When there are metal objects near the module, or when the module is placed inside a metal enclosure, signal attenuation can be very severe.
- When the power supply voltage is lower than the recommended value at room temperature, the lower the voltage, the lower the transmission power.

6.2 Module Is Easily Damaged

- Please check the power supply and ensure that it is within the recommended operating voltage range. Exceeding the maximum voltage may cause permanent damage to the module.
- Please check the stability of the power supply. The voltage must not fluctuate significantly or frequently.
- Please ensure that proper ESD protection procedures are followed during installation and use, as high-frequency components are sensitive to electrostatic discharge.
- Please ensure that the humidity is not excessively high during installation and use, as some components are moisture-sensitive devices.
- Unless there are special requirements, use of the module at excessively high or low temperatures is not recommended.

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Chapter 7 Soldering Work Instructions

7.1 Reflow Soldering Temperature

During reflow soldering, all temperatures refer to the temperature at the center of the package body, measured on the upward-facing surface of the package body (with the leads facing downward, i.e., the "live insect" orientation). If the module temperature is measured during reflow soldering in the opposite orientation (with the leads facing upward, i.e., the "dead insect" orientation), the measured Tp temperature must be within ±2°C of the Tp temperature measured in the "live insect" orientation to still meet the Tc requirements. Otherwise, the temperature profile should be adjusted to meet the Tc requirements. To accurately measure the actual peak temperature of the package body, it is recommended to use the method specified in JEP140 for furnace temperature testing.

To achieve better soldering results, it is recommended that the production workshop maintain a constant temperature of 25°C. When the temperature profile needs to be reconfigured for soldering components, the same type of carrier fixture should be used for reflow soldering, or a fixture that has been verified to have an equivalent thermal load.

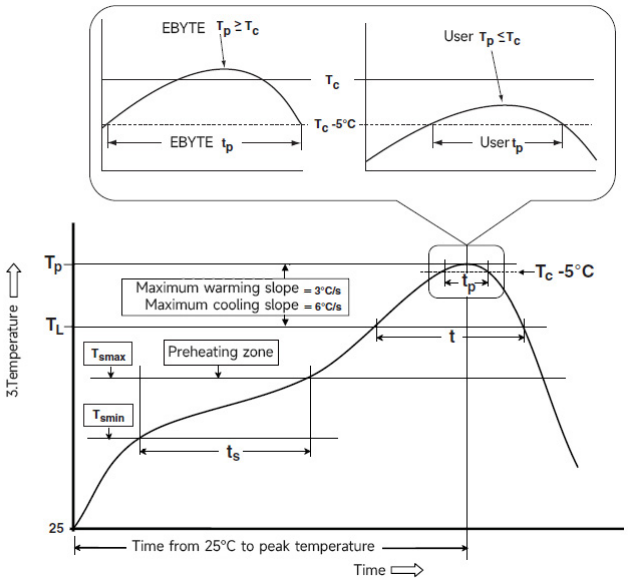
The reflow soldering profile in this document provides recommendations specifically for soldering EBYTE modules only and cannot be used to determine the actual assembly profile for the user's production process. During actual production, the user should develop the actual production assembly profile according to the specific manufacturing process and PCB design, and it should not exceed the limits specified in the following table:

Reflow Soldering Profile Characteristics		Lead-Based Process Assembly	Lead-Free Process Assembly
Preheating / Soaking	Minimum Temperature (Tsmin)	100℃	150℃
	Maximum Temperature (Tsmax)	150℃	200℃
	Time (Tsmin~Tsmin)	60-120 秒	60-120 秒
Ramp Rate (TL~Tp)		3°C/s, maximum	3°C/s, maximum
Liquidus Temperature (TL)		183℃	217℃
Time Above TL		60–90 seconds	60–90 seconds
Package Body Peak Temperature Tp		The user must not exceed the temperature specified on the product's **"Moisture Sensitivity Level"** label.	The user must not exceed the temperature specified on the product's **"Moisture Sensitivity Level"** label.
Time Within 5°C of the Specified Classification Temperature (Tc), Tp, see figure below		20 seconds	30 seconds
Cooling Rate (Tp~TL)		6°C/s, maximum	6°C/s, maximum
Time from Room Temperature to Peak Temperature		6 minutes, maximum	8 minutes, maximum
※ The tolerance for the peak temperature (Tp) of the temperature profile is defined as the user's upper limit.			

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7.2 Reflow Soldering Profile



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Revision History

Version	Revisio Date	Revision Description	Maintainer
1.0	2026-08-05	Initial Version	Lei

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